

Studies of thermal transport in Mo/Si multilayer structures

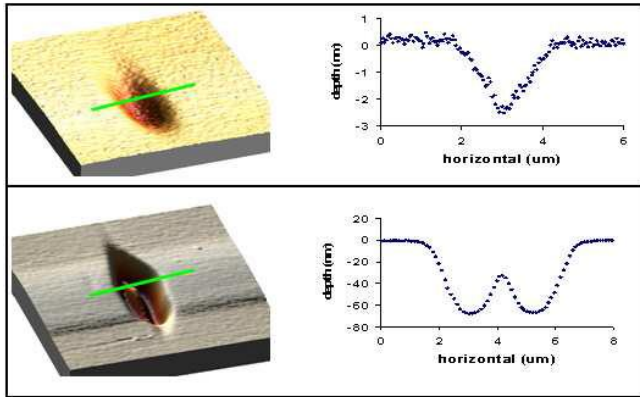
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Heat Loads on multilayer optics

- *High heat loads - radiation generated damage*



Sobierajski et al, EUV Source Workshop, Dublin (2014)

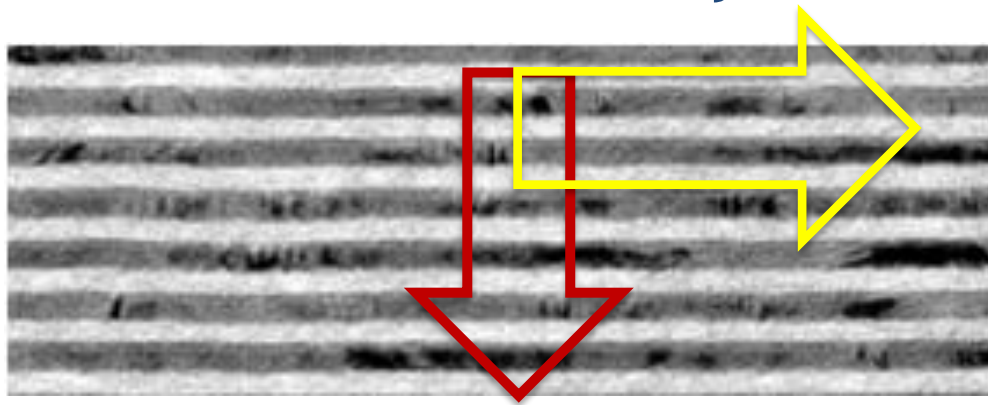
- *Moderate heat loads - heat induced imaging distortions*

!To be investigated

Heat transport in Mo/Si multilayers

Anisotropic heat transport

Lateral transport driven by electrons



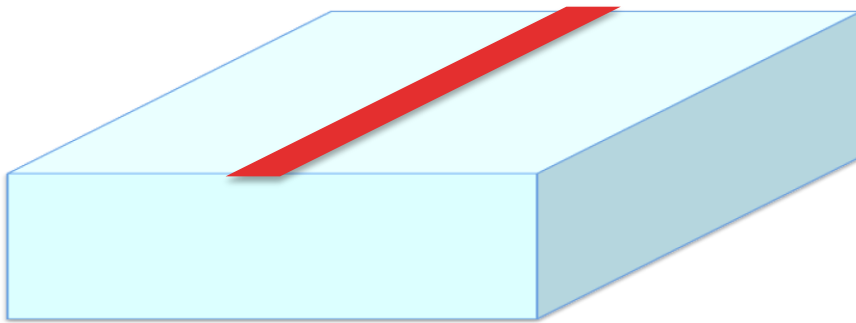
In-depth transport driven by lattice vibrations (phonons)

But how to characterize it?

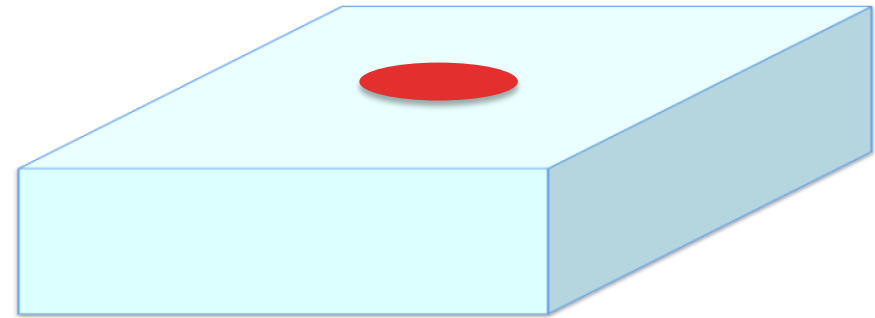
Techniques utilizing thermal waves

- ▶ Well-determined modulated heat source is applied on sample (thin film) surface

~Linear heater



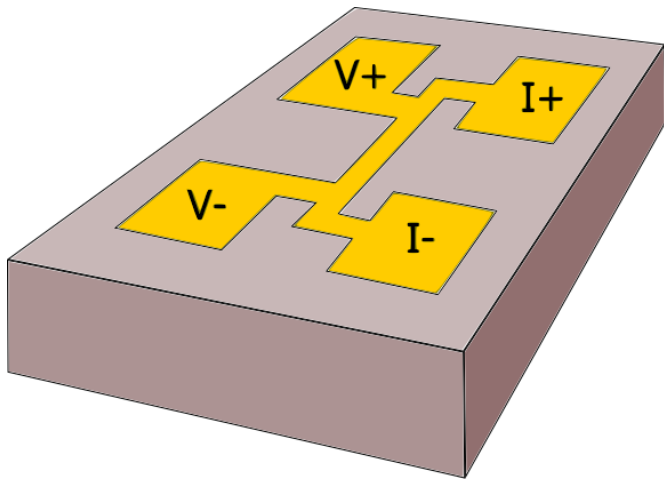
~Point heater



- ▶ Modulated heat source induces thermal wave propagation in sample volume
- ▶ Oscillation of surface temperature is measured to characterize thermal properties of the sample

3 ω technique

Geometry for thermal conductivity (k) measurements using 3 ω technique



Idea of 3 ω technique

Current:

$$I \sim \cos(\omega t)$$



Power dissipation:

$$P \sim I^2 \sim \cos(2\omega t)$$



Temperature $\Delta T(\omega)$ induced resistance oscillations:

$$\Delta R \sim \cos(2\omega t)$$

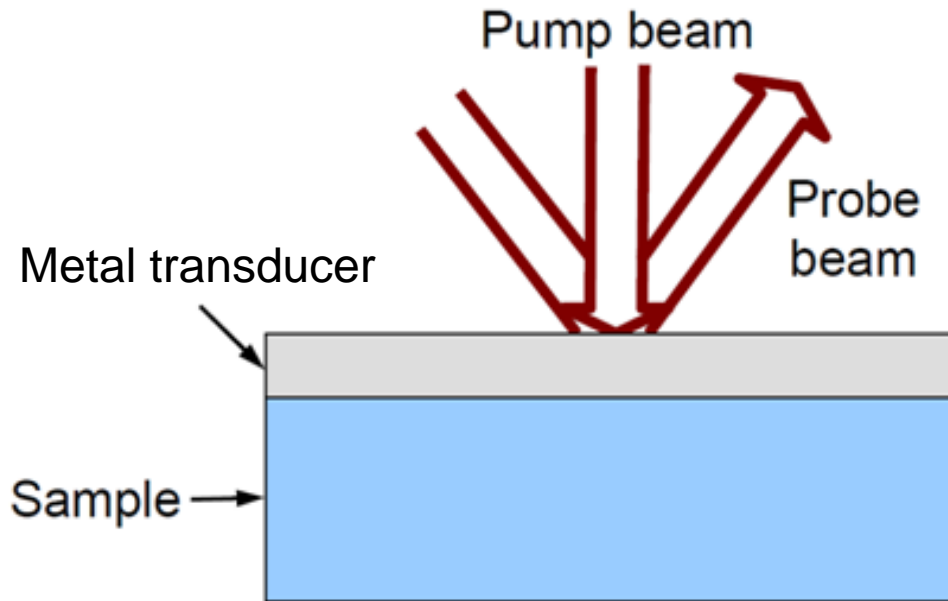


Small voltage oscillations at 3 ω :

$$\Delta V \sim I \cdot \Delta R \sim \cos(3\omega t) \text{ - main observable}$$

[D. G. Cahill Rev. Sci. Instrum. 61, 802 \(1990\)](#)

Transient thermoreflectance



Probe beam heats sample surface:

$$\Delta T$$

Optical constants and reflectivity depend on temperature

$$\Delta T \rightarrow \Delta R$$

Probe beam measures reflectivity changes

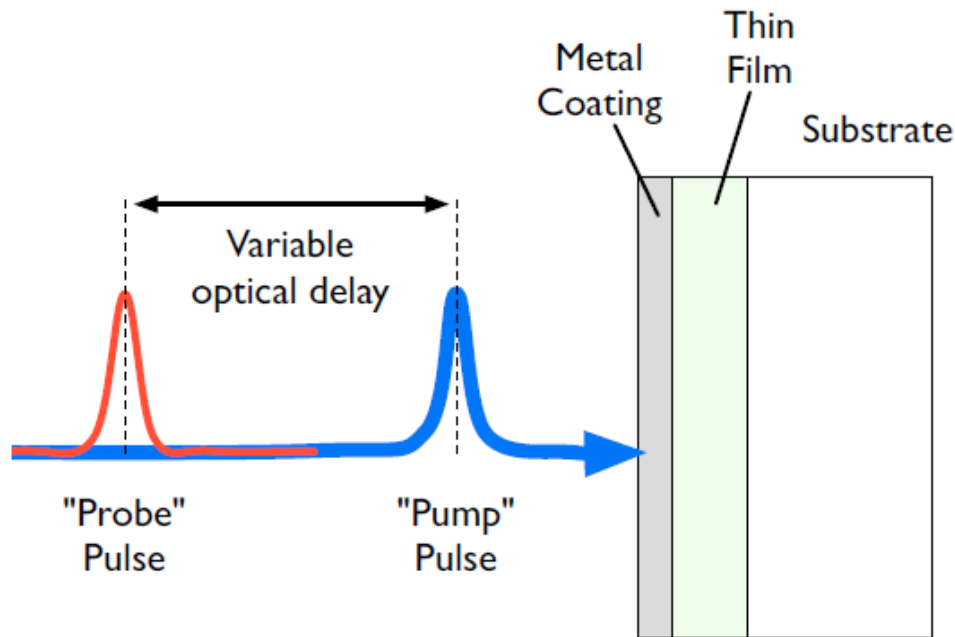
$$\Delta R_{\text{meas}} \rightarrow \Delta T_{\text{meas}}$$

D. Cahill, Review of scientific instruments 75 (12), 5119-5122 (2004)

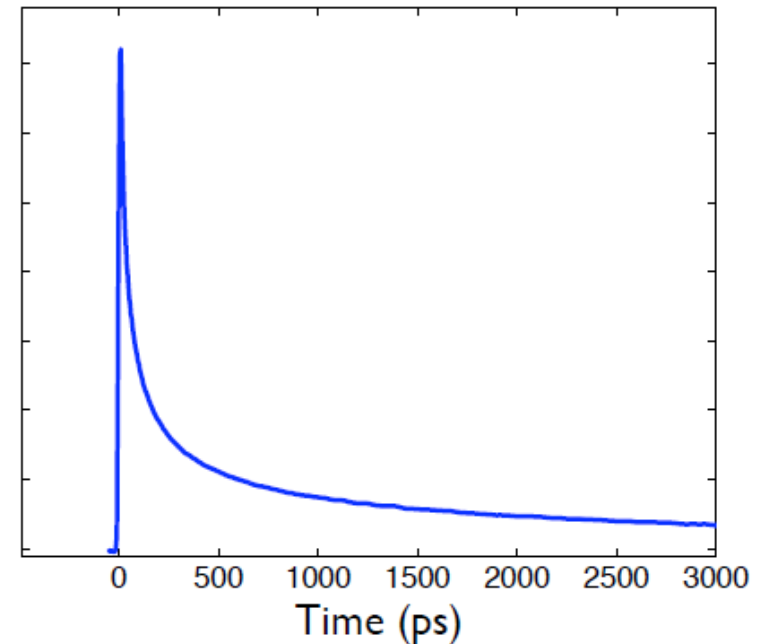
A.J.Schmidt et al, Review of Scientific Instruments 79 (11), 114902 (2008)

A.J.Schmidt et al, Review of Scientific Instruments 80 (9), 094901 (2009)

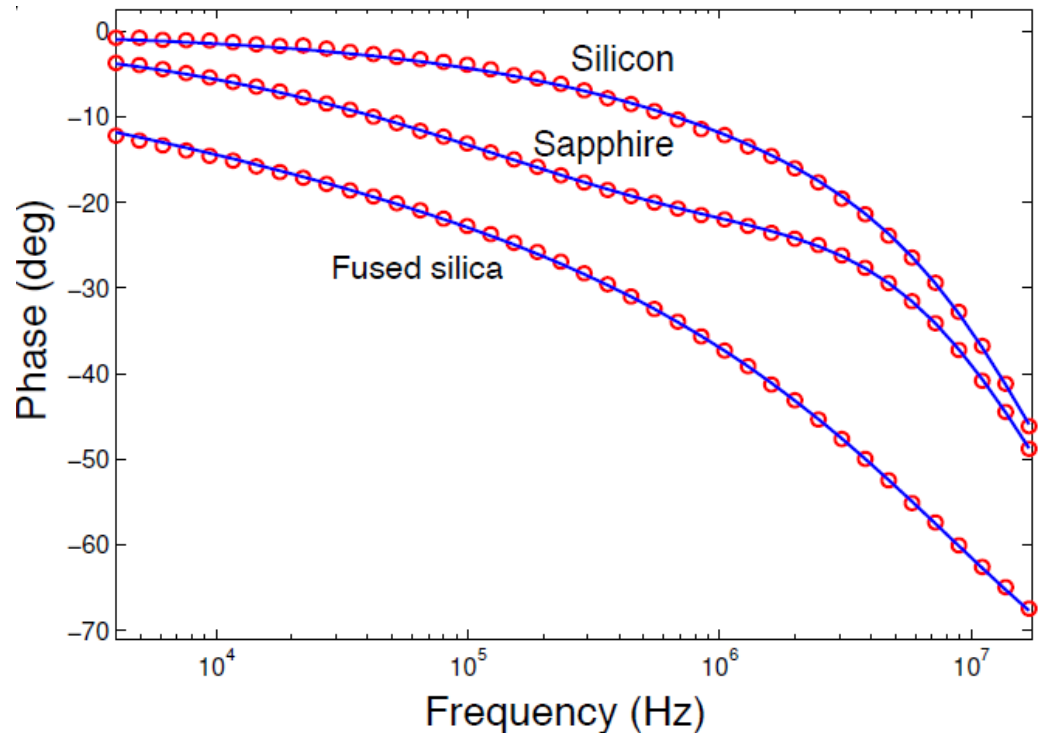
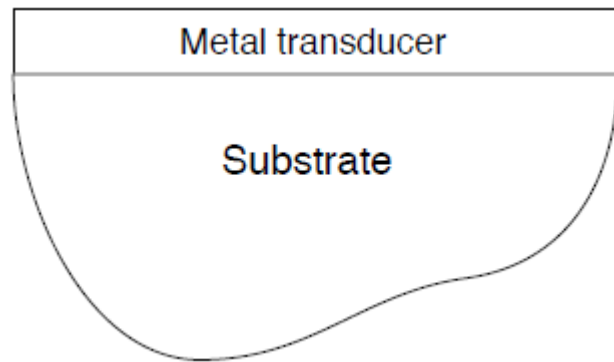
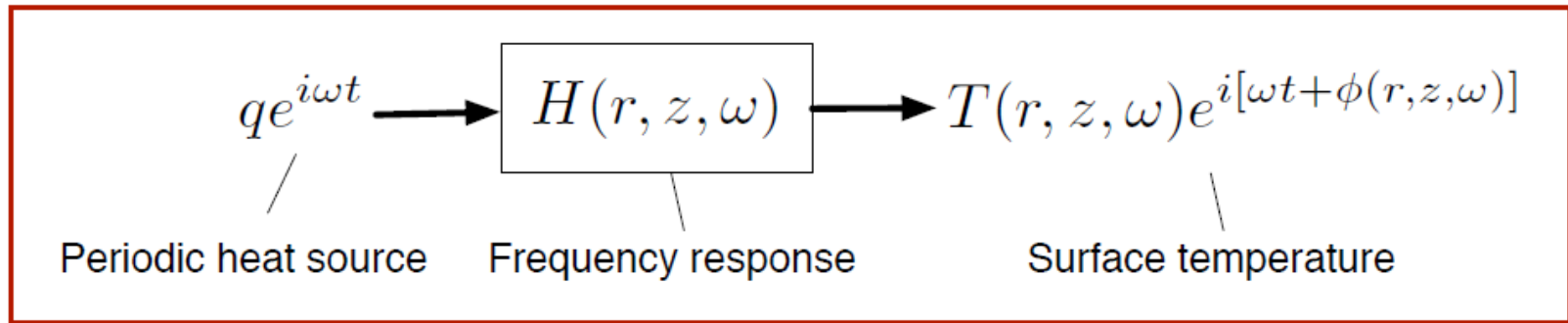
Time Domain ThermoReflectance (TDTR)



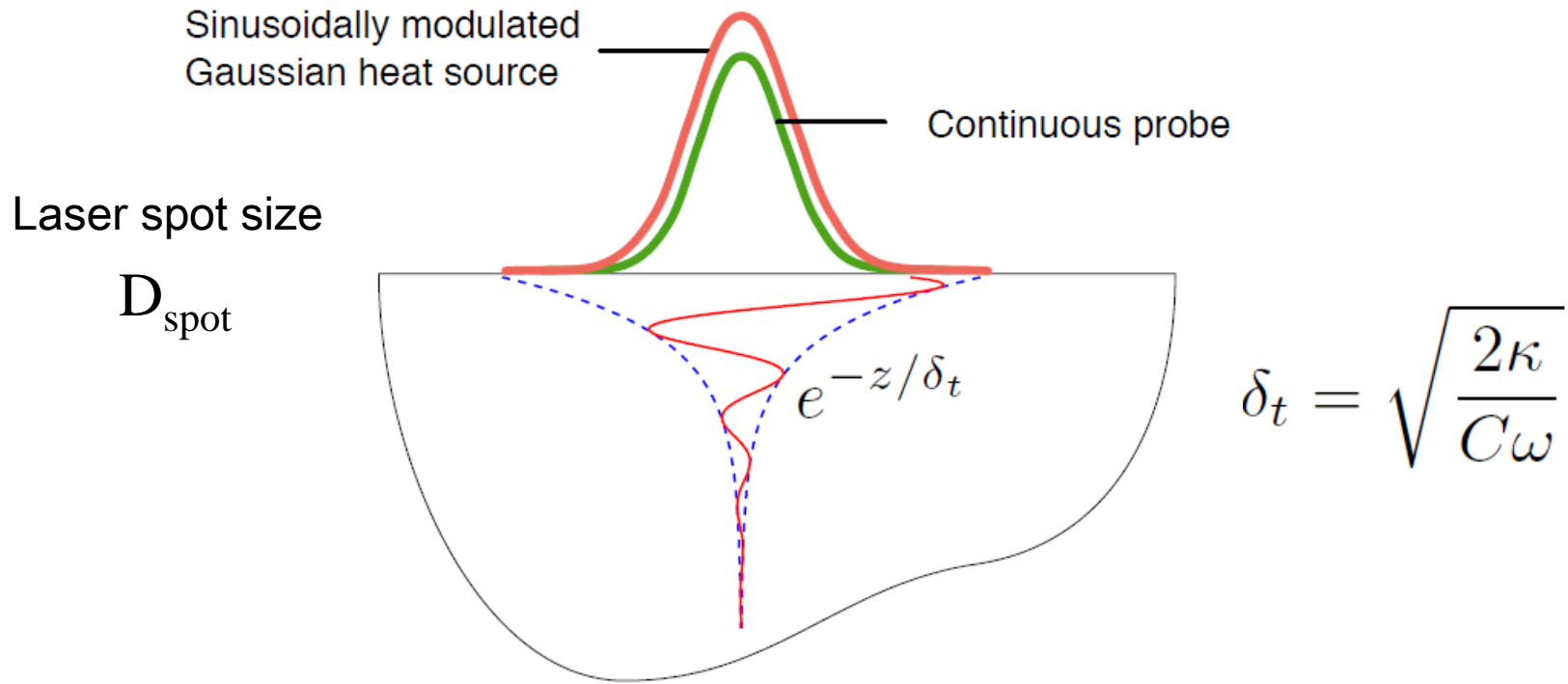
Reflectivity vs delay time



Frequency Domain ThermoReflectance (FDTR)

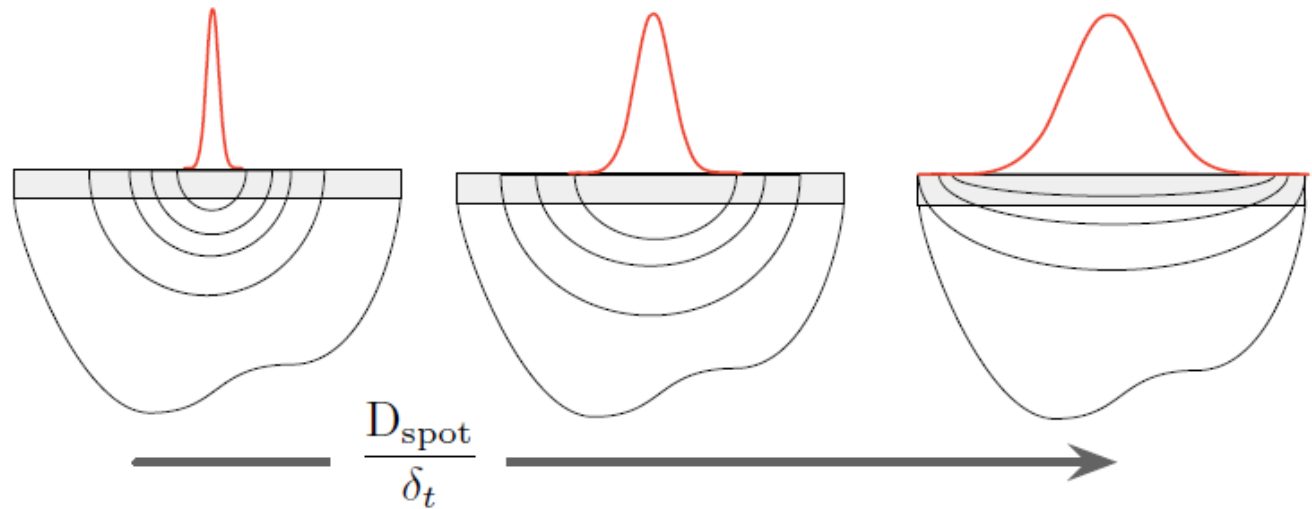
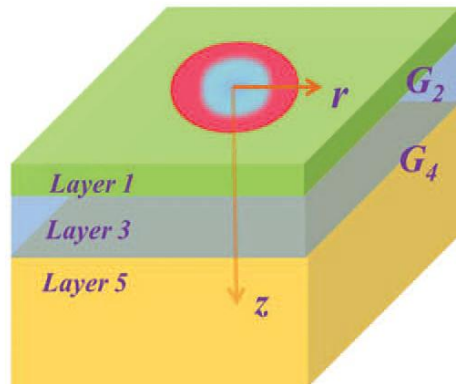


Thermal wave penetration depth



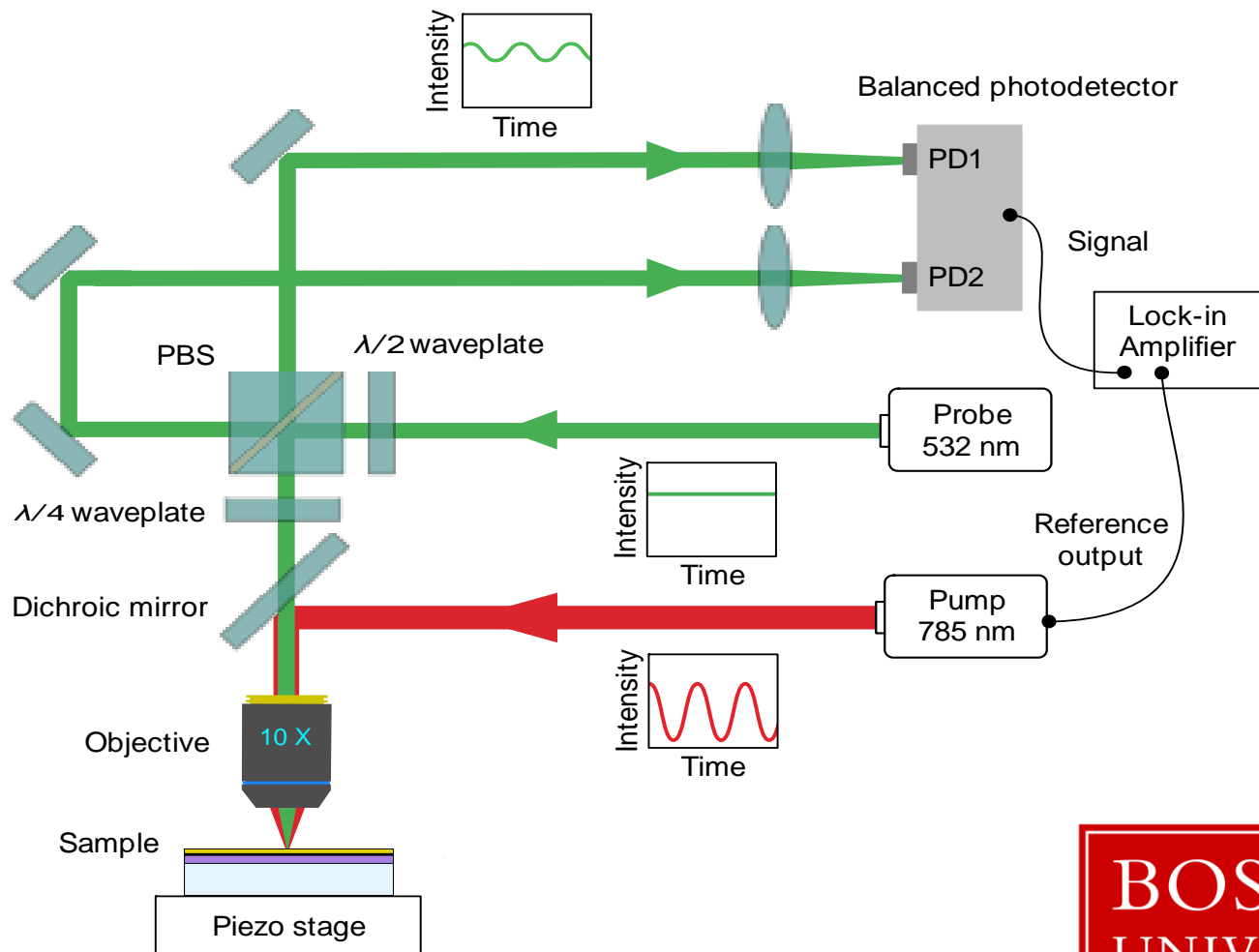
D_{spot}/δ_t ratio determines 'geometry' of thermal wave propagation

Switching between 1D and 3D heat conduction



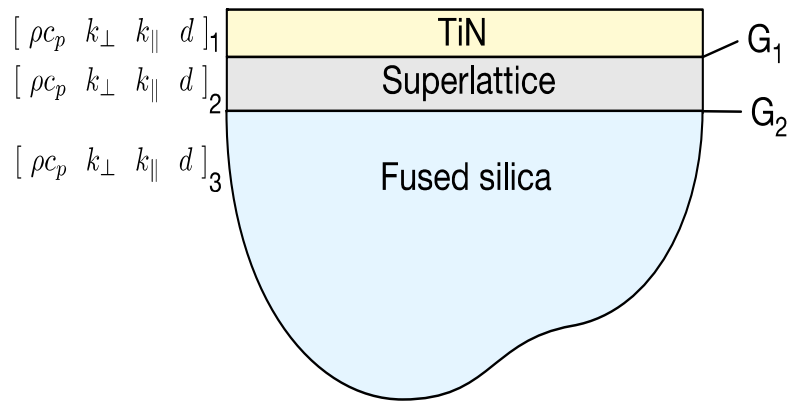
Thermal wave solution	Quasi-steady three-dimensional spherical wave		One-dimensional plane wave
ω	$\omega \ll \frac{32\kappa_r3}{R_{pp}C_3}$	$\omega \sim \frac{32\kappa_r3}{R_{pp}C_3}$	$\omega \gg \frac{32\kappa_r3}{R_{pp}C_3}$
Thermal property	$\sqrt{\kappa_{z3}\kappa_r3}$	$\sqrt{\kappa_{z3}\kappa_r3}, \sqrt{\kappa_{z3}C_3}$	$\sqrt{\kappa_{z3}C_3}$

FDTR setup

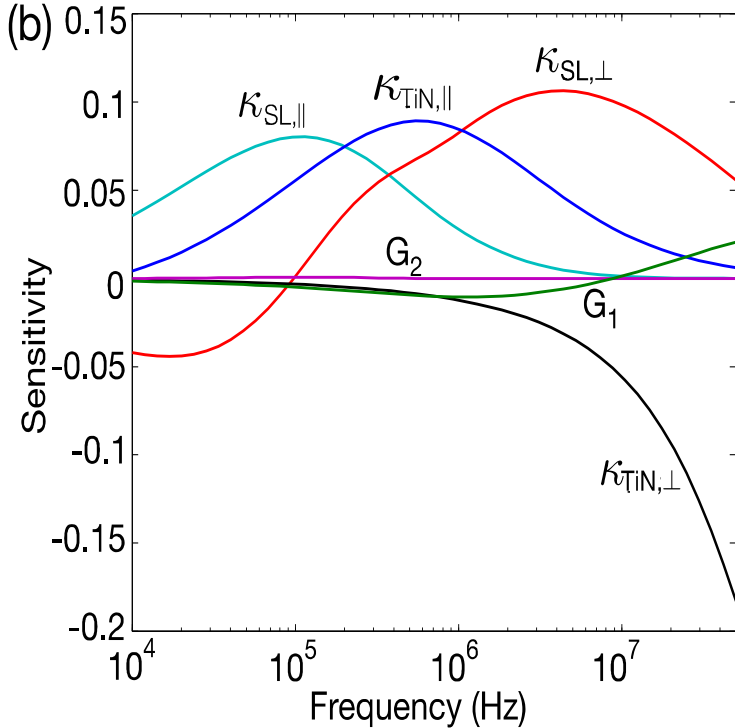


Parameters sensitivity

(a)

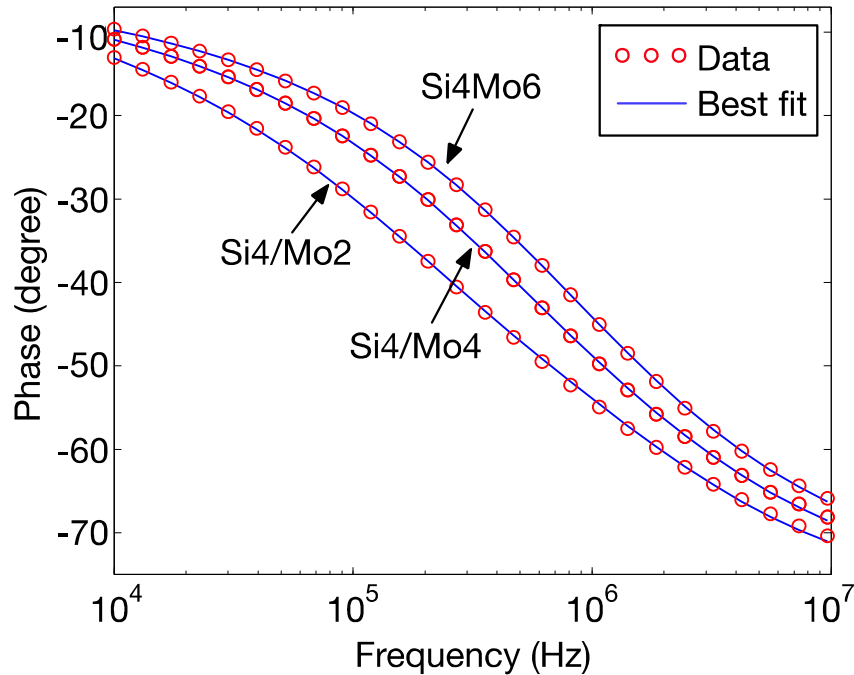


(b)



Transient thermoreflectance

Measured FDTR data



Multilayer properties obtained from data fit

Sample	$k_{\text{cross-plane}}$ (W m ⁻¹ K ⁻¹)	$k_{\text{in-plane}}$ (W m ⁻¹ K ⁻¹)
Si4/Mo2	0.75 ± 0.03	2.47 ± 0.14
Si4/Mo4	1 ± 0.03	8.48 ± 0.18
Si4/Mo6	1.3 ± 0.03	15.7 ± 0.24

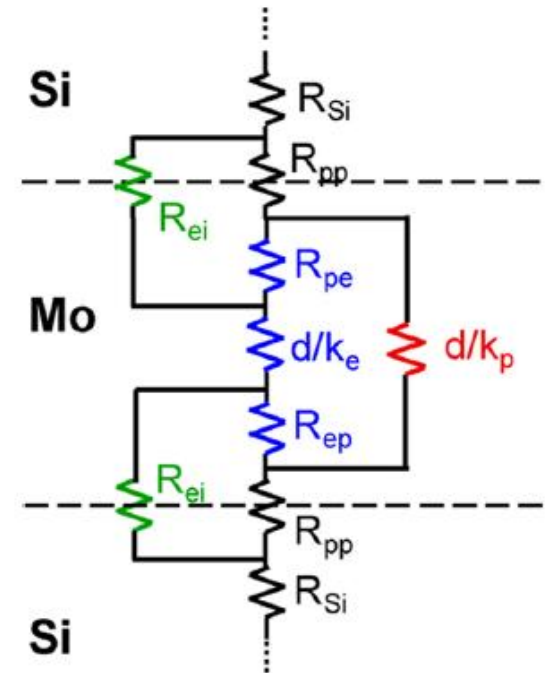
Cross-plane

$$R_{Mo/Si} = \frac{d_{Mo} + d_{Si}}{k_{\perp}} = \frac{d_{Mo}}{k_{Mo}} + \frac{d_{Si}}{k_{Si}} + \frac{1}{G_{Si-Mo}} + \frac{1}{G_{Mo-Si}}$$

k - thermal conductivity

G - thermal boundary conductance

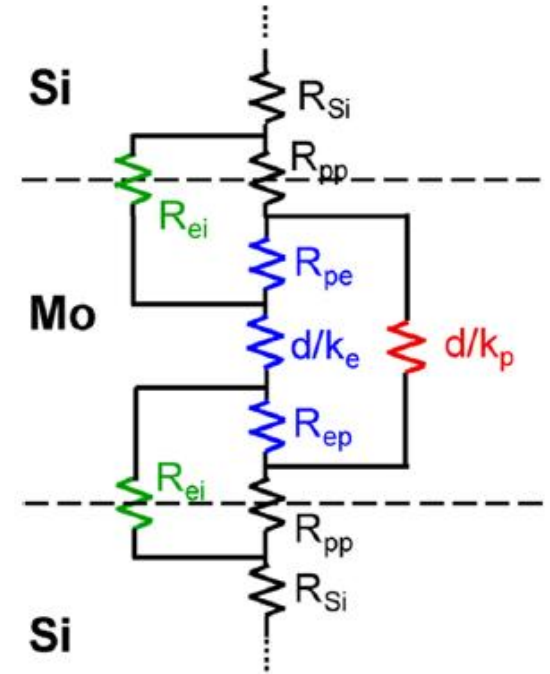
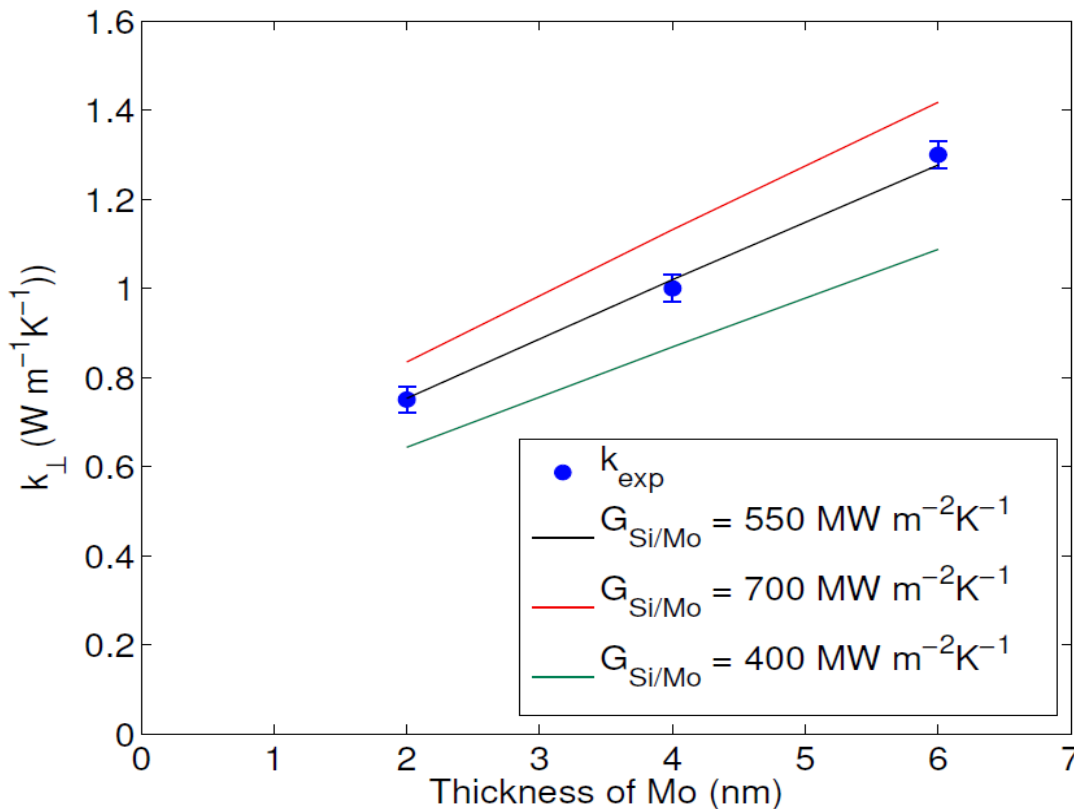
Material	k (W/m-K)
c-Si	149
a-Si	1
Mo	138



Low cross-plane k values for Mo/Si due to a-Si and interface scattering

Cross-plane

$$R_{Mo/Si} = \frac{d_{Mo} + d_{Si}}{k_{\perp}} = \frac{d_{Mo}}{k_{Mo}} + \frac{d_{Si}}{k_{Si}} + \frac{1}{G_{Si-Mo}} + \frac{1}{G_{Mo-Si}}$$



Analysis of in-plane thermal conductivity

Sample	$k_{\text{in-plane}}$ (W m ⁻¹ K ⁻¹)
Si4/Mo2	2.47 ± 0.14
Si4/Mo4	8.48 ± 0.18
Si4/Mo6	15.7 ± 0.24

Values of in-plane thermal conductivity are relatively small

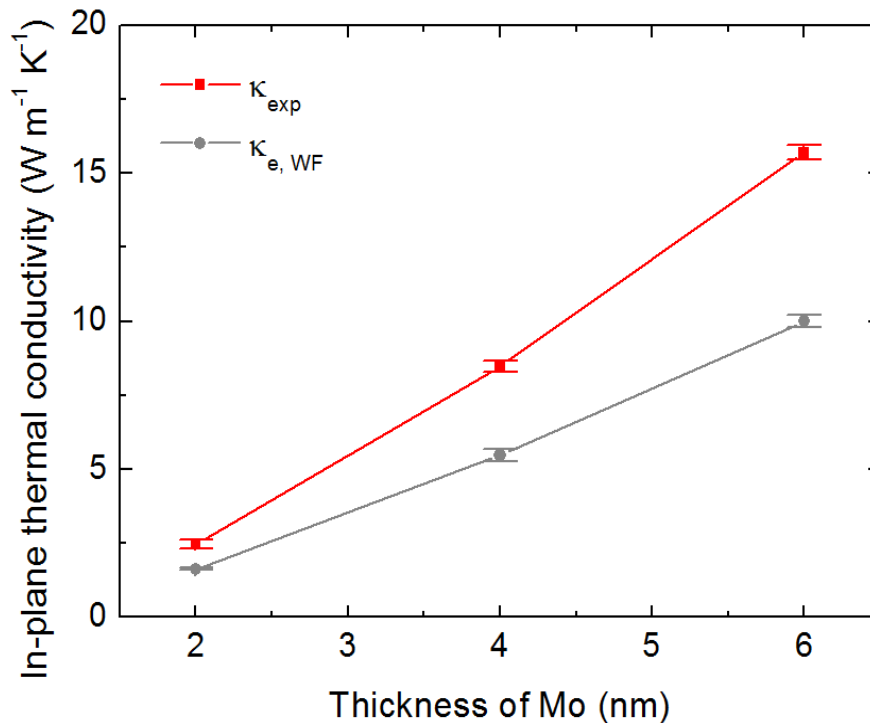
E.g. a-Si has $k \approx 1.0 \text{ Wm}^{-1}\text{K}^{-1}$.

- ➡ Lattice (phonon) contribution is significant
- ➡ Both contributions have to be analyzed

$$k = k_e + k_p$$

In-plane thermal conductivity

Electron contribution estimated using electrical conductivity and the Wiedemann-Franz law



$$\frac{k}{\sigma} = LT$$

➡ Phonons contribute about 35% to in-plane heat conduction

Summary

- ▶ *FDTR technique was adopted to characterize anisotropy of heat conduction in Mo/Si multilayer optics*
- ▶ *Cross-plane thermal transport governed by lattice vibrations. Small k values due to amorphous silicon and interface scattering*
- ▶ *In-plane thermal transport dominated by electrons, but lattice contribution is also considerable unlike in bulk metals*
- ▶ *Anisotropy ratio ($k_{\text{in-plane}}/k_{\text{cross-plane}}$) ranging 3.3 to 12.1 demonstrated for Mo/Si with varied Mo thickness from 2 to 4 nm, respectively*

Thank you for your attention



Wiedemann-Franz law

WF law is the ratio of the electronic contribution of the thermal conductivity (κ) to the electrical conductivity (σ) of a metal, and is proportional to the temperature (T):

$$\frac{\kappa}{\sigma} = LT$$

Theoretical value for Lorenz number (! No account for electron-phonon coupling):

$$L_0 = \frac{\pi^2}{3} \left(\frac{k_B}{e} \right)^2 = 2.44 \times 10^{-8} [\text{W}\Omega\text{K}^{-2}]$$

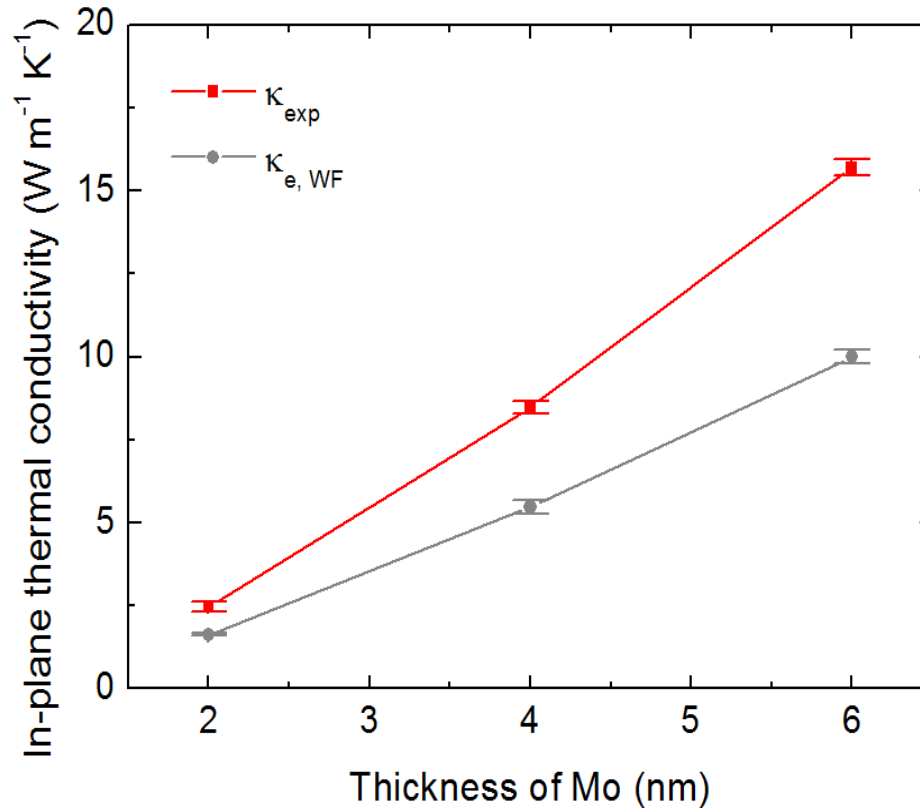
Corrected Lorenz number (Stojanovic et al *PRB* **82** 075418 (2010)) :

$$L_c = L_0 \left[1 + \frac{3}{\pi^2} \left(\frac{2}{Z} \right)^{2/3} \left(\frac{\theta_D}{T} \right)^2 \right]^{-1}$$

Four-probe measurement of electrical conductivity

Sample	Number of periods	Si layer (nm)	Mo layer (nm)	$\sigma \cdot 10^6 \Omega^{-1}\text{m}^{-1}$
Si4/Mo2	160	4	2	0.312 ± 0.005
Si4/Mo4	120	4	4	1.043 ± 0.044
Si4/Mo6	96	4	6	1.898 ± 0.040

In-plane thermal conductivity



➡ Phonons contribute about 35% to in-plane heat conduction

How to estimate phonon contribution

Assumption of zero silicide layers, i.e. perfect Mo/Si structure:

$$k_p = \Gamma k_{p,Mo} + (1 - \Gamma) k_{p,Si}$$

$$\Gamma = \frac{d_{Mo}}{d_{Mo} + d_{Si}}$$

We used measured value for a-Si:

$$k = 1.01 \text{ Wm}^{-1}\text{K}^{-1} \text{ (FDTR for 500 nm sputtered Si)}$$

For Mo phonon contribution cannot be measured, needs to be estimated

How to estimate phonon contribution

General formulae for any type of heat carriers:

$$k = \frac{1}{3} C_V v \lambda$$

C_V - heat capacity, v - velocity of heat carriers, λ - mean free path

Phonons:

Heat capacity can be estimated using the Debye theory

$$C_V = 9Nk_B \left(\frac{T}{\theta_D} \right)^3 \int_0^{\theta_D/T} \frac{x^4 e^x}{(e^x - 1)^2} dx$$

Velocity of phonons equals speed of sound

$$v_s = (v_l^{-3} + 2v_t^{-3})^{-1/3}$$

Phonon mean free path

Two estimates are possible here

(Terry M. Tritt *Thermal conductivity: theory, properties and applications* 2004)

1. Minimum thermal conductivity limit

For highly disordered (amorphous) media phonon mean free pass is set to interatomic distance

$$\lambda = a$$

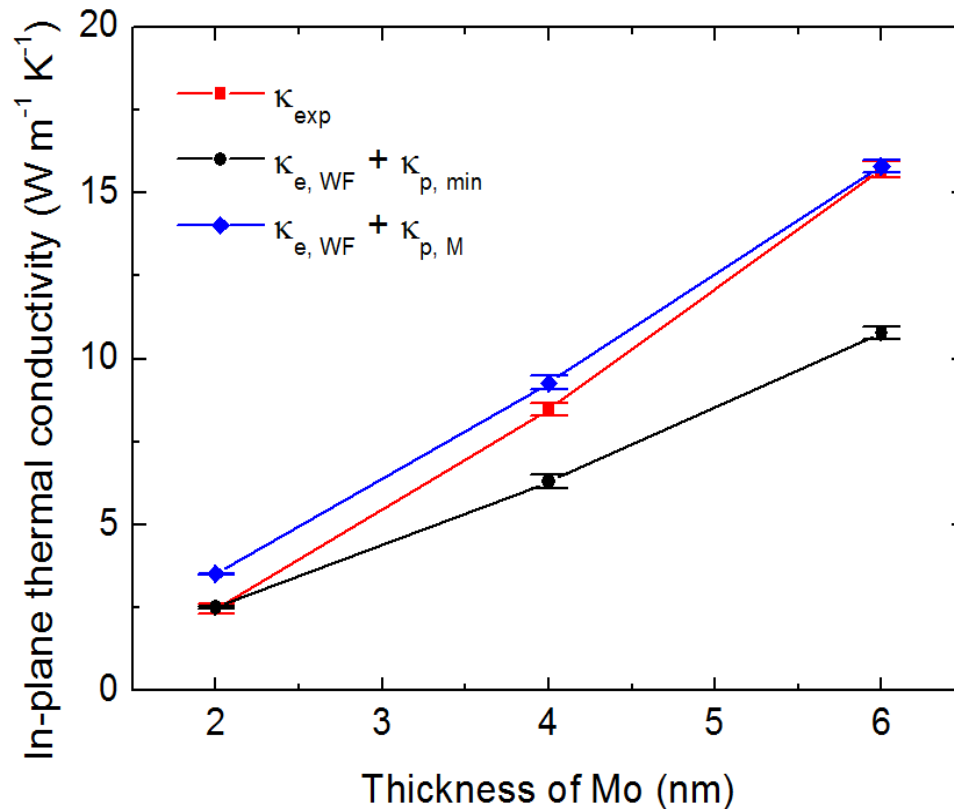
2. Matthiessen's rule

For nanostructured (polycrystalline) materials

$$\frac{1}{\lambda} = \frac{1}{\lambda_{Lattice}} + \frac{1}{\lambda_{Defects}}$$

In-plane thermal conductivity

Measured data vs estimated electron + phonon contributions



- ➔ For 2 nm Mo minimum thermal cond limit gives better matching
- ➔ For 4 and 6 nm Mo Matthiessen's rule rules